JUNE 1984-REVISED MAY 1986

- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- P-N-P Inputs Reduce DC Loading
- Outputs Have 25-Ω Series Resistor, So No External Resistors are Required
- Package Options Include Plastic "Small Outline" Packages, Plastic and Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs
- Dependable Texas Instruments Quality and Reliability

#### description

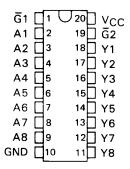
These octal buffers and line drivers are designed to drive capacitive input characteristics of MOS devices and have the performance of the popular SN54ALS240A/SN74ALS240A series. At the same time, they offer a pinout with inputs and outputs on opposite sides of the package. This arrangement greatly enhances printed-circuit-board layout.

The three-state control gate is a 2-input AND with active-low inputs such that if either  $\overline{G}1$  or  $\overline{G}2$  is high, all eight outputs are in the high-impedance state.

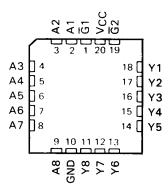
The 'ALS2540 offers inverting data and the 'ALS2541 offers true data at the outputs.

The SN54ALS' is characterized for operation over the full military temperature range of  $-55\,^{\circ}\text{C}$  to  $125\,^{\circ}\text{C}$ . The SN74ALS' is characterized for operation from  $0\,^{\circ}\text{C}$  to  $70\,^{\circ}\text{C}$ .

SN54ALS2540, SN54ALS2541 . . . J PACKAGE SN74ALS2540, SN74ALS2541 . . . DW OR N PACKAGE (TOP VIEW)

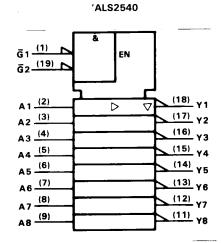


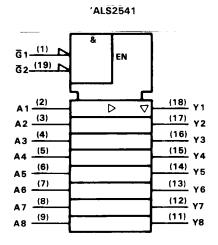
SN54ALS2540, SN54ALS2541 . . . FK PACKAGE (TOP VIEW)



JUNE 1984-REVISED MAY 1986

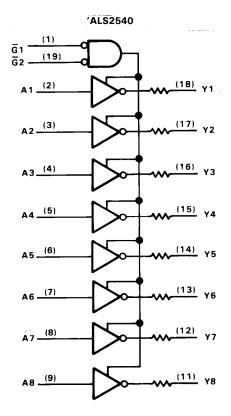
#### logic symbols†

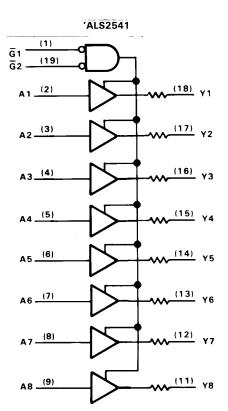




<sup>†</sup>These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

#### logic diagrams (positive logic)





All output resistors are 25  $\boldsymbol{\Omega}.$ 

JUNE 1984-REVISED MAY 1986

absolute maximum ratings over operating	ng free-air tem	perature range	(unless othe	rwise noted)
Supply voltage, VCC				7 V
Input voltage				7 V
Voltage applied to a disabled 3-state o	output			5.5 V
Operating free-air temperature range:	SN54ALS2540	SN54ALS254	1	-55°C to 125°C
	SN74ALS2540	SN74ALS254	1	0°C to 70°C
Storage temperature range				-65°C to 150°C

#### recommended operating conditions

			SN54ALS2540 SN54ALS2541			SN74ALS2540 SN74ALS2541		
		MIN	NOM	MAX	MIN	NOM	MAX	
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH ,	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
<sup>Т</sup> ОН	High-level output current			-0.4			-0.4	mA
<sup>I</sup> OL	Low-level output current			12			12	mA
TA	Operating free-air temperature	- 55		125	0		70	°C

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				SI	N54ALS:	2540	SN	74ALS2	540		
		TF0T 0	SI	V54ALS	2541	SN	74ALS2	541	UNIT		
۴	PARAMETER TEST CONDITION		ONDITIONS	MIN	TYP <sup>†</sup>	MAX	MIN	TYP <sup>†</sup>	MAX	UNIT	
VIK		$V_{CC} = 4.5 V$ ,	I <sub>I</sub> = -18 mA			- 1.2			-1.2	V	
Vон		$V_{CC} = 4.5 \text{ V to } 5.5$	$5 \text{ V}, \text{ I}_{OH} = -0.4 \text{ mA}$	Vcc-	2		Vcc-	2		V	
\		V <sub>CC</sub> = 4.5 V,	I <sub>OL</sub> = 1 mA		0.15	0.5		0.15	0.5	V	
VOL		$V_{CC} = 4.5 \text{ V},$	I <sub>OL</sub> = 12 mA		0.35	0.8		0.35	0.8	] <b>`</b>	
lozh		$V_{CC} = 5.5 V$ ,	$V_0 = 2.7 \text{ V}$			20			20	μΑ	
<sup>I</sup> OZL		$V_{CC} = 5.5 V$ ,	$V_0 = 0.4 V$			- 20			- 20	μΑ	
ТОН		$V_{CC} = 4.5 \text{ V},$	V <sub>0</sub> = 2 V	- 15			- 15			mA	
TOL		$V_{CC} = 4.5 \text{ V},$	V <sub>0</sub> = 2 V	30			30			mA	
T <sub>I</sub>		$V_{CC} = 5.5 V$ ,	V <sub>I</sub> = 7 V			0.1			0.1	mA	
ΊΗ		$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 2.7 V			20			20	μΑ	
ΊL		V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.4 V		-	-0.1			-0.1	mA	
10‡		$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.25 \text{ V}$	- 15		<b>- 70</b>	- 15		<b>- 70</b>	mA	
			Outputs high		5	10		5	10		
	'ALS2540	$V_{CC} = 5.5 V$	Outputs low		13	22		13	22	mA	
١.			Outputs disabled		11	19		11	19	]	
Icc			Outputs high		6	14		6	14		
	'ALS2541 V <sub>CC</sub> =	$V_{CC} = 5.5 V$	Outputs low		<b>1</b> 5 <b>2</b> 5 15		15	25	mA		
			Outputs disabled		13.5	22		13.5	22	]	



 $<sup>^{\</sup>dagger}$  All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25 °C.  $^{\ddagger}$  The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I<sub>OS</sub>.

JUNE 1984-REVISED MAY 1986

#### 'ALS2540 switching characteristics (see Note 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5 \text{ V},$ $C_L = 50 \text{ pF},$ $R1 = 500 \Omega,$ $R2 = 500 \Omega,$ $T_A = 25 ^{\circ}C$	C <sub>L</sub> R1 R2 T <sub>A</sub>	C = 4.5  V = 50 pF, = 500 $\Omega$ , = 500 $\Omega$ , = MIN to	MAX		UNIT
			'ALS2540	+	LS2540		L\$2540	4
			TYP	MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	Α	٧	7.5	2	14	2	12	ns
tPHL	ן ^ ו	ī	5.6	2	13	2	11	] '''
<sup>t</sup> PZH	G	V	9	5	18	5	15	ns
<sup>t</sup> PZL	7 3 1	1	12.6	8	24	8	20	] '''
t <sub>PHZ</sub>	- G	Y	4	1	12	1	10	ns
, tPLZ	7 '	1	7	2	14	2	12	113

#### 'ALS2541 switching characteristics (see Note 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$ = 5 V, $C_L$ = 50 pF, R1 = 500 Ω, R2 = 500 Ω, $T_A$ = 25 °C	C <sub>L</sub> R1 R2	C = 4.5 V = 50 pF, = 500 Ω, = 500 Ω, = MIN to			UNIT
			'AL\$2541	SN54A	LS2541	SN74A	LS2541	
			TYP	MIN	MAX	MIN	MAX	
tPLH		Y	8.7	2	17	2	15	
tPHL	┥ ^	ĭ	7	2	14	2	12	ns
<sup>t</sup> PZH	G		9	5	18	5	15	
<sup>t</sup> PZL	7 6 1	ť	12.6	8	24	8	20	ns
tPHZ	- G	Υ	4	1	12	1	10	ns
tPLZ	7 '	1	7	2	14	2	12	113

NOTE 1: Load circuit and voltage waveforms are shown in Section 1.







#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74ALS2540N	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SN74ALS2541DW	OBSOLETE	SOIC	DW	20		Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS2541DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS2541DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS2541DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS2541N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS2541NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS2541NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS2541NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS2541NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

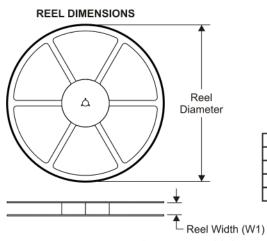
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



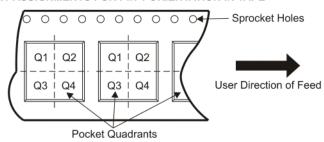
#### TAPE AND REEL INFORMATION



# TAPE DIMENSIONS + K0 - P1 - B0 W Cavity - A0 -

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS2541DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ALS2541NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1





\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS2541DWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74ALS2541NSR	SO	NS	20	2000	346.0	346.0	41.0

#### **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



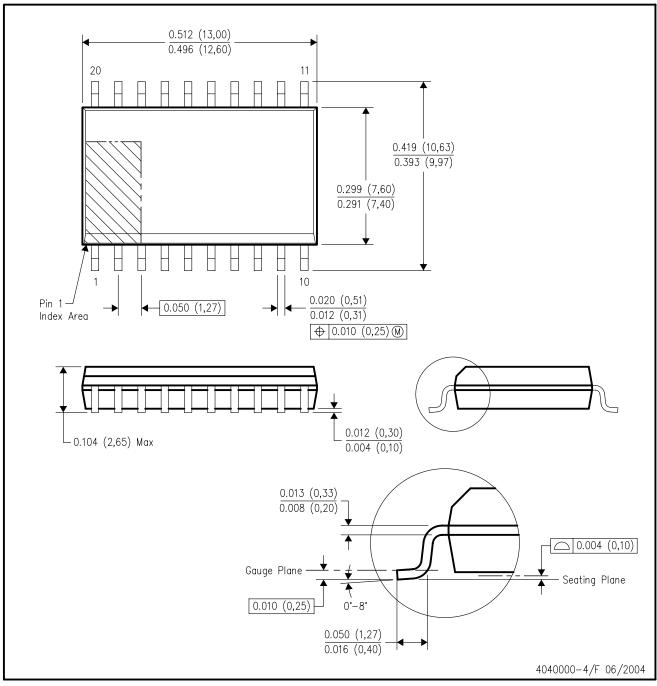
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# DW (R-PDSO-G20)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



## N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

#### **Products Amplifiers** amplifier.ti.com Data Converters dataconverter.ti.com DSP dsp.ti.com Clocks and Timers www.ti.com/clocks Interface interface.ti.com Logic logic.ti.com Power Mamt power.ti.com Microcontrollers microcontroller.ti.com www.ti-rfid.com RF/IF and ZigBee® Solutions www.ti.com/lprf

Applications	
Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2008, Texas Instruments Incorporated